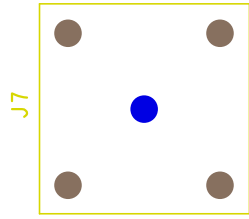
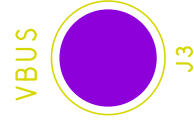


ASSEMBLY TOP

RENESAS

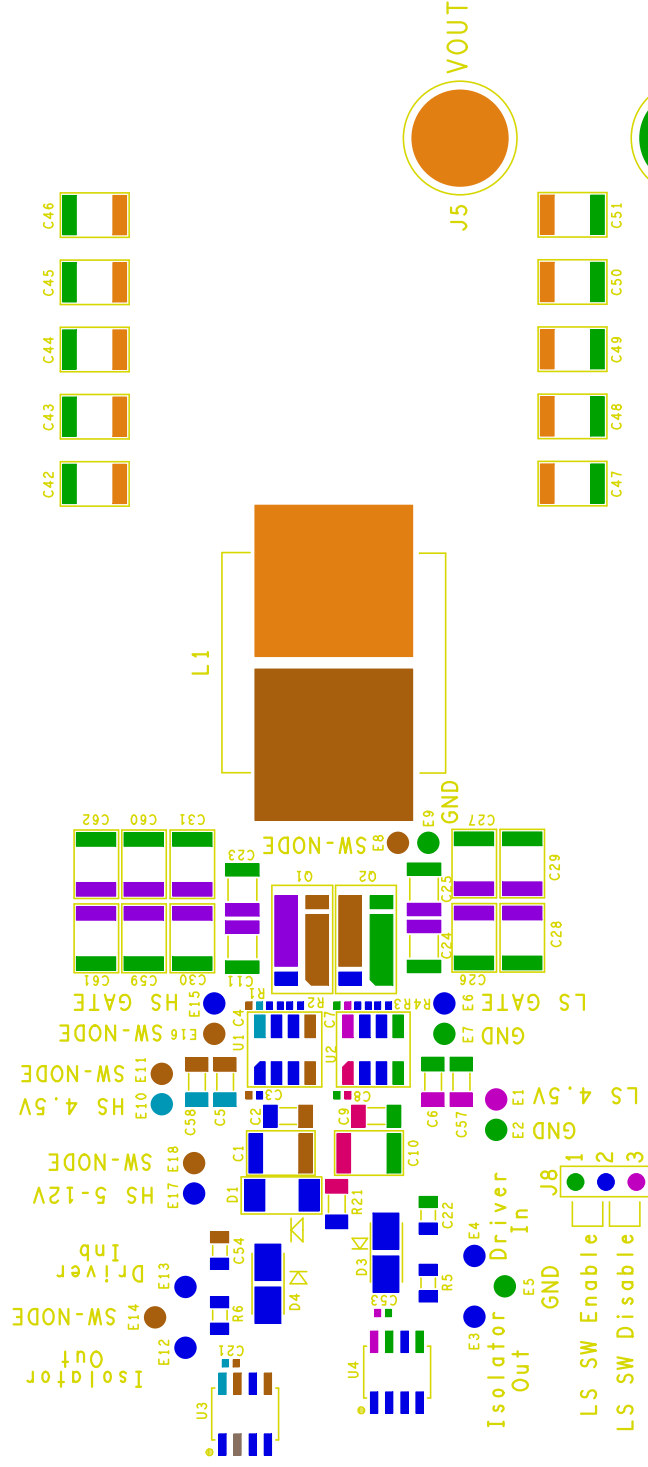
DATE: 09-28-2018



PWM
Max 10Vpk

**intersil**

ISL73040SEHEV4Z Rev. A



ISL73040SEH: Low Side GaN

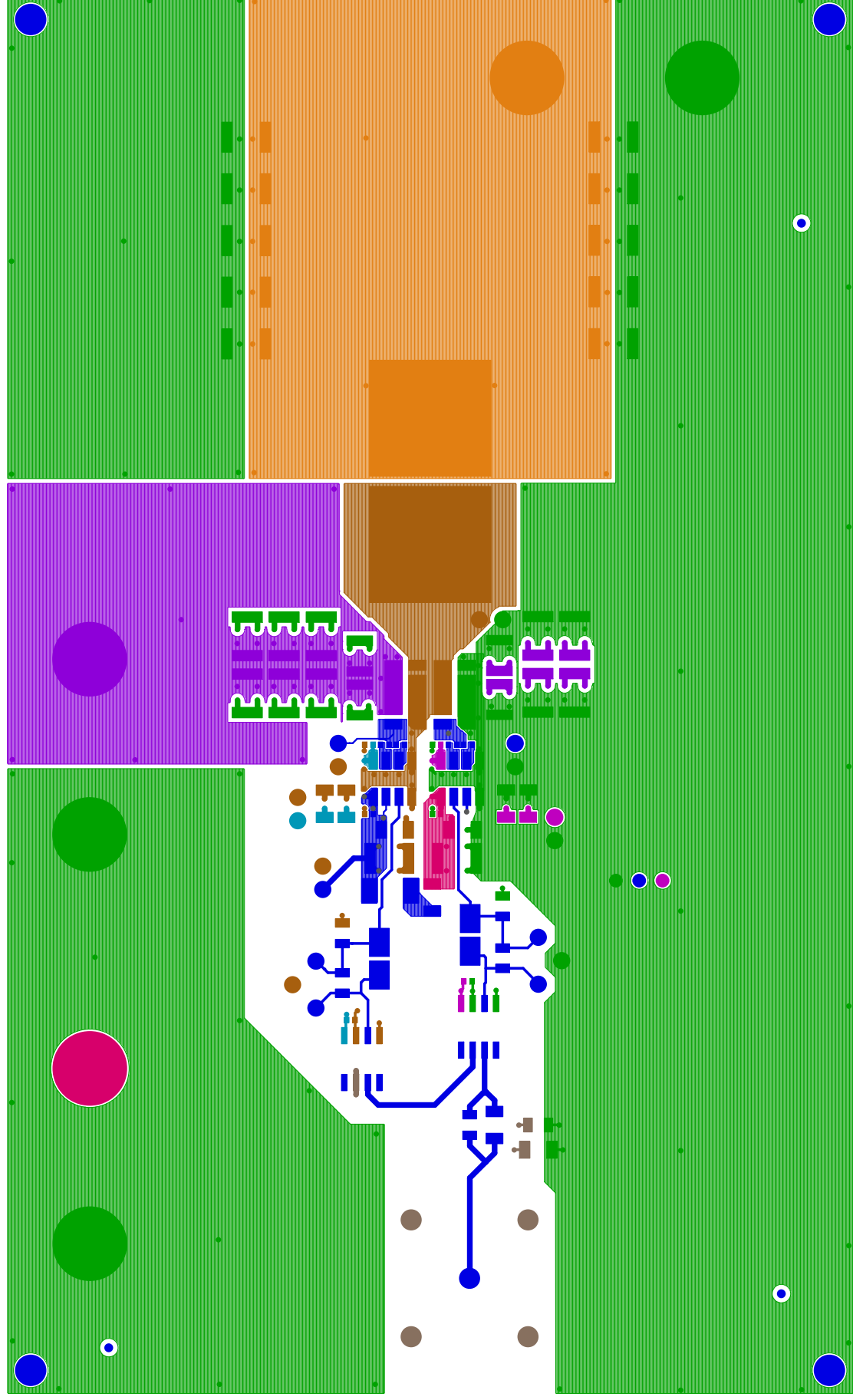
FET Driver

ISL73024SEH: 200V GaN FET

SILKSCREEN TOP

RENE SAS

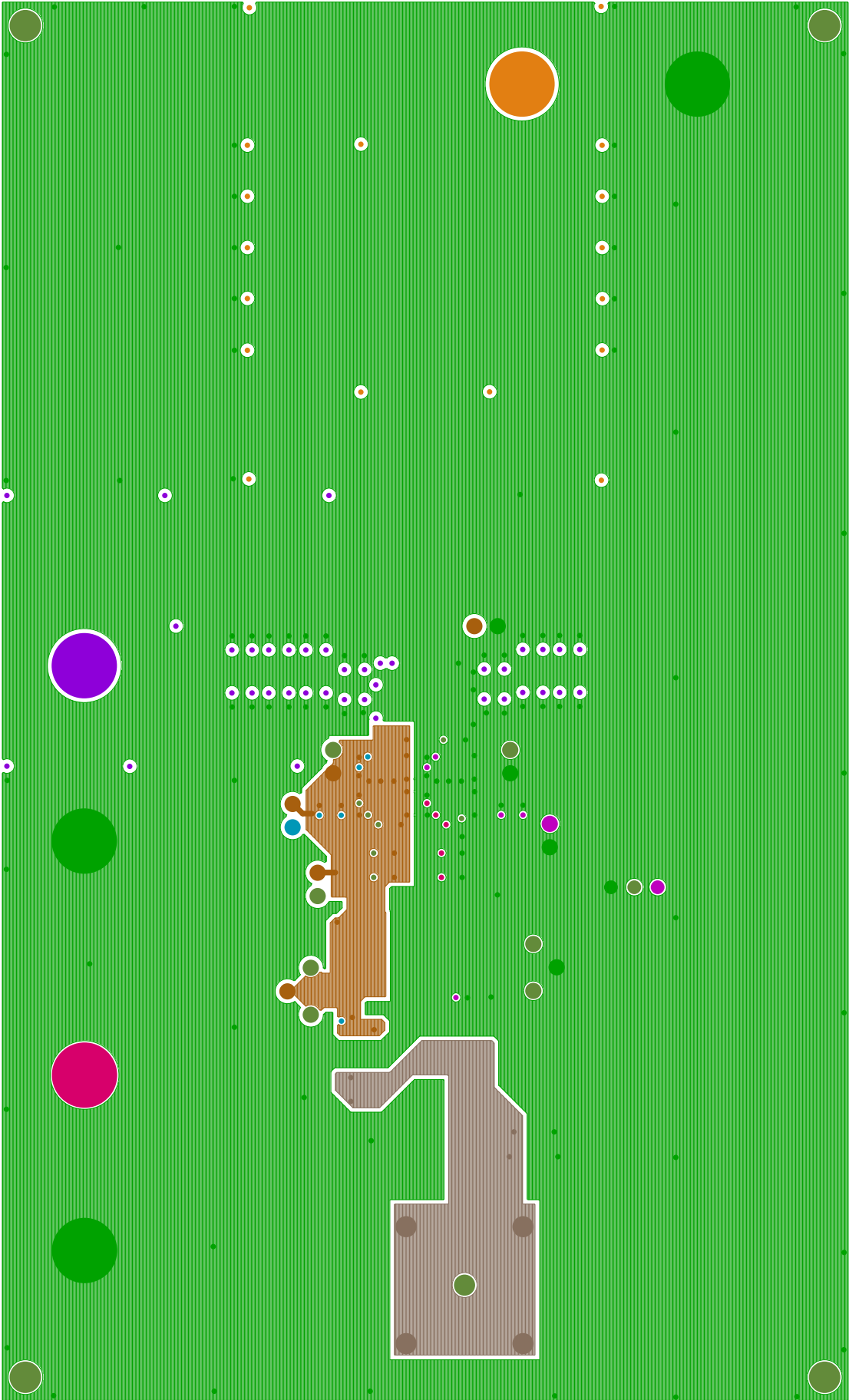
DATE: 09-28-2018



LAYER 1 (COMPONENT SIDE)

RENESAS

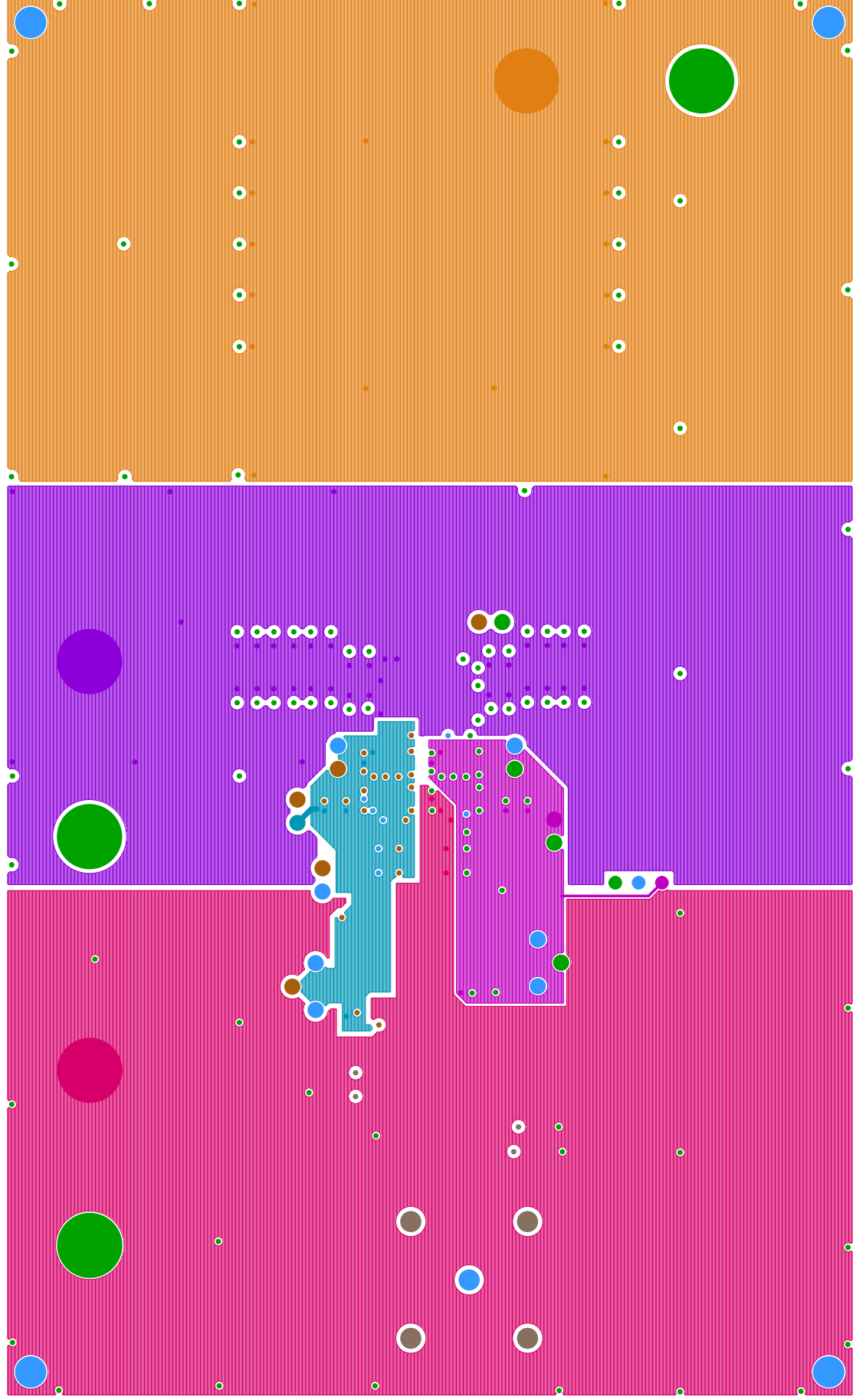
DATE: 09-28-2018



LAYER 2

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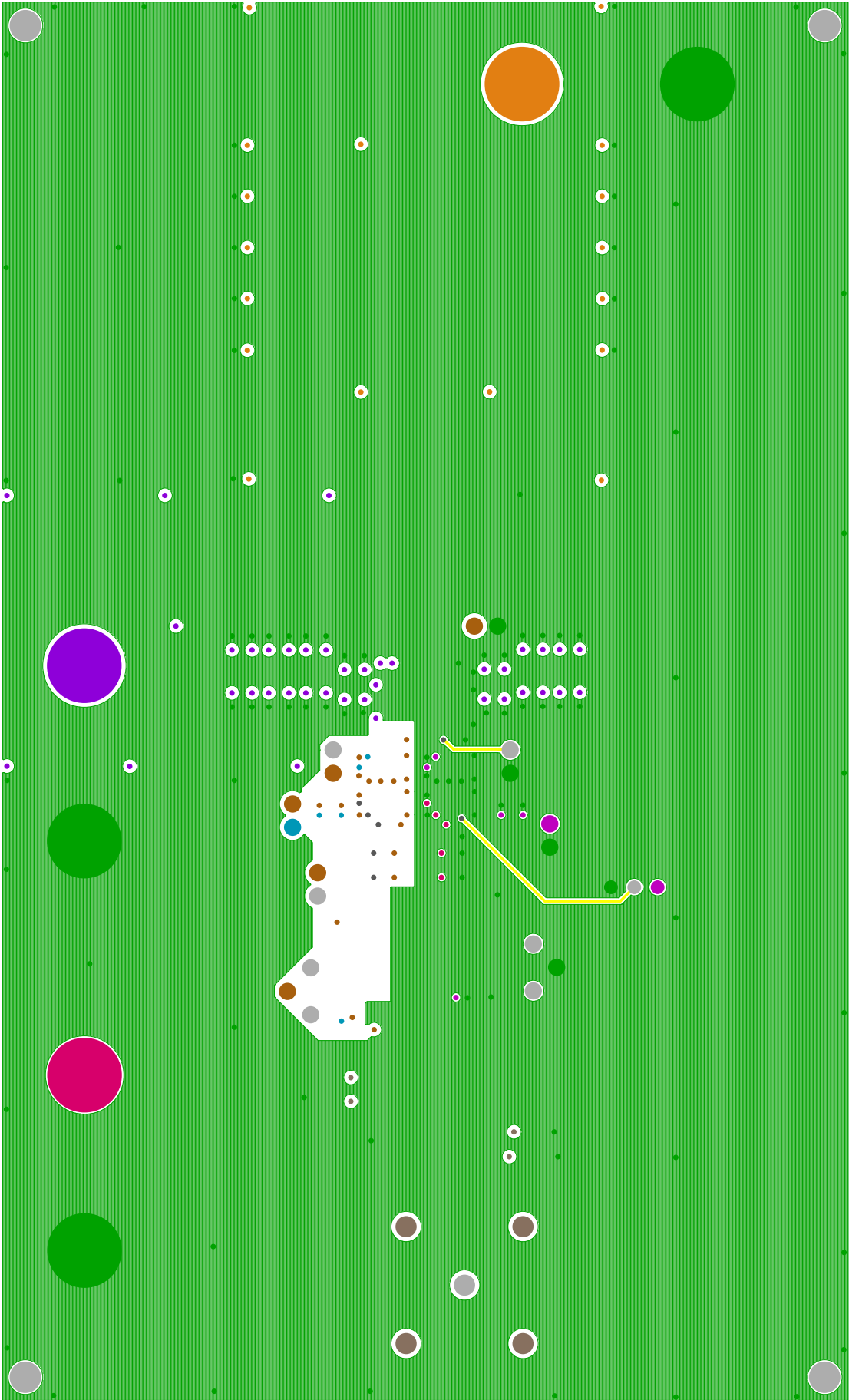
DATE: 09-28-2018



LAYER 3

RENESAS

DATE: 09-28-2018

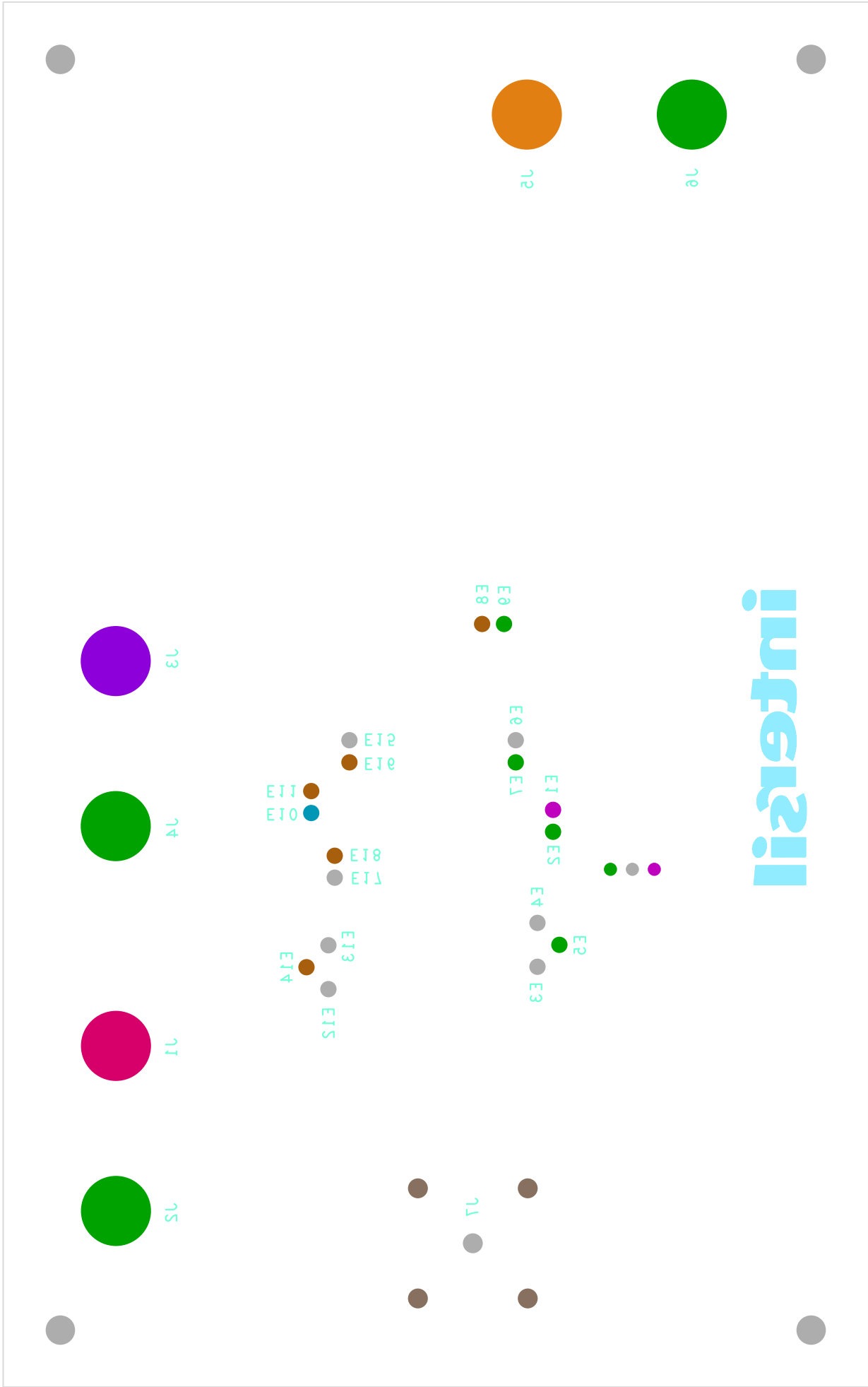


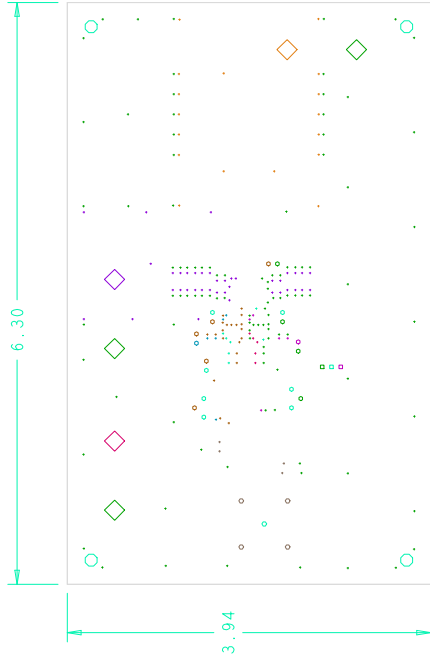
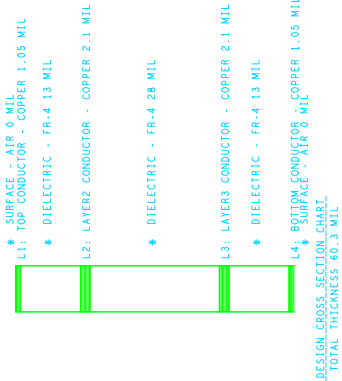
LAYER 4

RENESAS

DATE: 09-28-2018

SILKSCREEN BOTTOM





DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	15.0	+2.0/-2.0	PLATED	206
•	40.0	+2.0/-2.0	PLATED	3
◦	44.0	+2.0/-2.0	PLATED	18
◦	52.0	+3.0/-3.0	PLATED	5
○	125.0	+3.0/-3.0	PLATED	4
◇	219.0	+3.0/-3.0	PLATED	6

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT), 1 OZ COPPER MINIMUM BOARD FINISH: LEADED SOLDER, HOT AIR SOLDERED LEVELED (HASL)
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED ISL73040SEHV4ZA_IPC356.IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
- 10 TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
- 11 FINISHED BOARD THICKNESS: 60.7 MILS +/- 7 MILS
SEE DESIGN CROSS SECTION CHART

Drawn By:	Date Drawn:	Engineer:
Tim Klemann	09/28/2018	Kiran Bernard
Released By:	Date Released:	
Updated By:	Date Updated:	
intertii		WASP#
		ITEM ID
		REV.
		ISL73040SEHV4Z
		A
FILENAME:		SHEET
~/ISL73040SEH/ISL73040SEHV4ZA		1 OF 1